

# MODEL DM-800B

## Full-Automatic Die Attach Sheet Lamination System

### Outline

The DM-800B is the ideal full-automatic system for laminating die sheet on 6", 8" 50  $\mu$  thickness wafers.

### Features

- Capable of handling 6", 8" 50  $\mu$  thickness wafer and aligning precisely.
- Uniform lamination by using special heater and roller control system.
- After cure function inside, laminating the wafer by wafer one by one.
- Applicable to coinstack wafer Jar. ( option )



Specification		DM-800B
Throughput		25 wafers/hour( Depend on data setting )
Wafer Size		6 inch, 8 inch
Tape Width		6 inch :W 190 ~ 240mm 、 8 inch :W 235 ~ 240mm
Utilities	Power	AC200V Single phase 50 / 60Hz 4.0 KVA
	Air	Pressure 0.5Mpa 100NI/min
	Vacuum source	74Kpa
Dimensions		D 1,080 x W 1,330 x H 1,930mm( For wafer Jar type,width is 1330+560mm )
Weight		600 kg

System appearance and specifications are subject to change without prior notice from the supplier.

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